ocket No.: MUH-12728

thereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22813-1450, on the date indicated below.

Date: August 20, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant ·

Hans Weber et al.

Applic. No.

10/631,350

Filed

July 31, 2003

Title

Method for Forming a Channel Zone of a Transistor and PMOS

Transistor

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner for Patents

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

Bobby J. Daniel et al.: "Modeling of the CoolMOSTM Transistor – Part I: Device Physics", IEEE Transactions on Electron Devices, Vol. 49, No. 5, May 2002, pp. 916-920.

Respectfully submitted,

For Applicants

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Date: August 20, 2003

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/bmb

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AUG 2 2 2003 STATE TRANSP FQM PTO-1449 (SUBSTITUTE) Attorney Docket No.: Applic. No. 10/631,350 MUH-12728 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Applicant Hans Weber et al. INFORMATION DISCLOSURE STATEMENT BY APPLICANT Filing Date Group Art Unit (37 CFR 1.98(b)) July 31, 2003 U.S. PATENT DOCUMENTS **EXAMINER** INITIALS PATENT NO. DATE **PATENTEE** CLASS **CLASS** Α В С D Ε F G Н FOREIGN PATENT DOCUMENT DOCUMENT NO. CLASS DATE COUNTRY J Κ L Μ N

DATE TRANSL. SUB **CLASS** YES | NO OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.) o Bobby J. Daniel et al.: "Modeling of the CoolMOSTM Transistor – Part I: Device Physics", IEEE Transactions on Electron Devices, Vol. 49, No. 5, May 2002, pp. 916-920 P **EXAMINER** DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with

next communication to applicant.